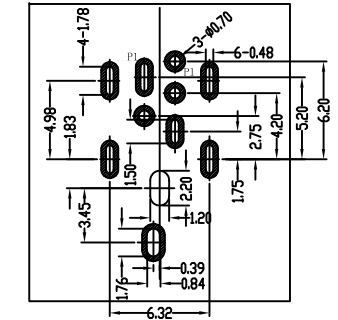
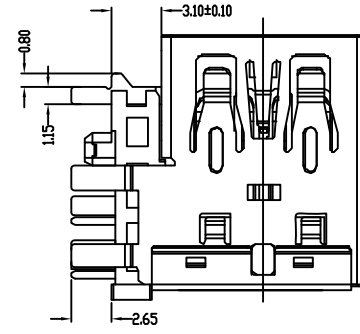
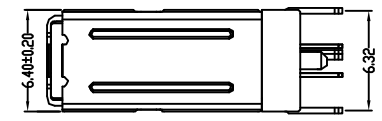
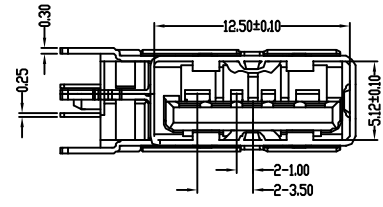
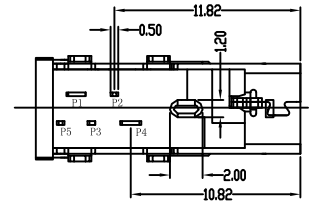
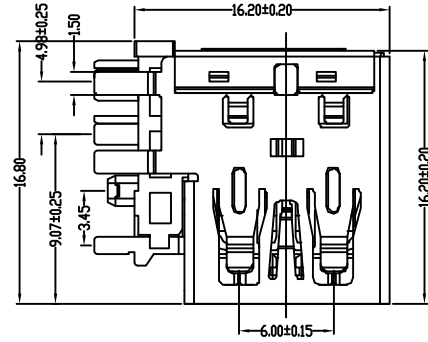
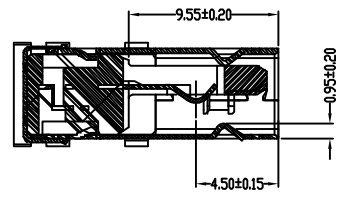


MAPX	MODIFICATION	DATE



PCB Layout(T=0.20)

NOTES;

1. MATERIALS AND FINISHES;

HOUSING MATERIAL;LCP R845 UL94V-0 HF.

PIN MATERIAL;C7035 TM-04 T=0.25mm

CONTACT AREAL;PLATING Au30u"min.Ni 80u" Min

SOLDER TAIL;MATTE TIN 180u" Min

SHELL MATERIAL;PHO,BRONZE T=0.30mm

PLATED Ni 50u" MIN

BACKSHELL MATERIAL;SUS304 T=0.20mm
2. ELECTRICAL CHARACTERISTICS

CONTACT RESISTANCE; 30m Max.

DIELECTRIC WITHSTANDING VOLTAGE;AC 500V R, M, S,

INSULATION RESISTANCE;1000M MIN
3. MECHANICAL CHARACTERISTICS;

CONTACT INSERTION FORCE;35 N MAX

CONTACT SEPARATION FORCE; 10 N MIN(AFTER CYCLE 1500)
4. MATERIAL MUST FULFILL GWI4-11 SALCOMP HAZARDOUS SUBSTANCES MANAGEMENT STANDARD LATEST VERSION.

产品图 PRODUCT CHART DWG		深圳市精拓金电子有限公司							
公差一览表 TOLERANCE UNLESS OTHERWISE		单位 UNITS	MM	制图 DRAWING	许榕强	制图料号 PRODUCT PART NO.			
X.	±0.15	X.	±5.°	比例 SCALE	1:1	审核 CHKD	郭治富	产品名称 PRODUCT NAME	USB AF SIDE 90° DIP TYPE
.X	±0.10	.X	±2.°	日期 DATE	2016-09-09	核准 APPD	黄国荣	角法 VIEW	
.XX	±0.05	.XX	±1.°					版本 VER	AD
.XXX	±0.03	.XXX	±0.5°						